

ABSTRACT

WIRE BONDING ~~DEVICE~~ APPARATUS

5 A wire bonding ~~device~~ apparatus 100 is provided with: a bonding stage ~~7~~ on which a semiconductor chip ~~20~~ is mounted; a wire bonding unit ~~40~~ comprising including a capillary ~~1~~ for bonding a bonding wire ~~200~~ to the semiconductor chip ~~20~~, a Z-axis drive ~~unit~~ section-5 for reciprocating the capillary ~~1~~, and a tool XY-stage ~~6~~ for causing the capillary ~~1~~ and the Z-axis drive ~~unit~~ section-5 to be moved along a two-dimensional plane intersecting ~~the reciprocating direction~~ a direction of reciprocation; and a base ~~70~~ having an optical system ~~10~~ and an optical system XY-stage ~~11~~ for causing the optical system ~~10~~ to be moved along a two-dimensional plane intersecting ~~the reciprocating direction~~ a direction of reciprocation, the base ~~70~~ having the wire bonding unit ~~40~~ mounted-attached thereto. The wire bonding unit ~~40~~ is attached ~~mounted~~ to a first portion ~~71a~~ of the base ~~70~~, and the optical system XY-stage ~~11~~ is attached ~~mounted~~ to a second portion ~~71b~~ of the base ~~70~~ which is separate from the first portion ~~71a~~.

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Representative drawing: Fig. 1